Integrated Device Technology, Inc.
2975 Stender Way, Santa Clara, CA - 95054

PRODUCT/PROCESS CHANGE NOTICE (PCN)

PCN #: **L0306-02** DATE: 7/3/03

Product Affected: Please see attachment for the product list

Date Effective: October 2, 2003

MEANS OF DISTINGUISHING CHANGED DEVICES:

- ☐ Product Mark
- ☐ Back Mark
- ■ Date Code Prefix (Stepping) change. Please see attachment for details.
- ☐ Other

Contact: Bimla Paul
Title: Quality Assurance Manager
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Attachment:: ■ Yes ☐ No

Samples: Available upon request.

DESCRIPTION AND PURPOSE OF CHANGE:

- ☐ Die Technology
- ☐ Wafer Fabrication Process
- ☐ Assembly Process
- ☐ Equipment
- ☐ Material
- ☐ Testing
- ■ Manufacturing Site
- ☐ Data Sheet
- ☐ Other

Selected Logic products will be transferred to IDT's wafer fab facility in Hillsboro, Oregon (Fab 4). There is no change in die technology.

Please see attachment for the product list and qualification data.

RELIABILITY/QUALIFICATION SUMMARY:

Please see attachment for qualification data.

CUSTOMER ACKNOWLEDGMENT OF RECEIPT:

IDT records indicate that you require written notification of this change. Please use the acknowledgement below or E-Mail to grant approval or request additional information. If IDT does not receive acknowledgement within 30 days of this notice it will be assumed that this change is acceptable.
IDT reserves the right to ship either version manufactured after the process change effective date until the inventory on the earlier version has been depleted.

Customer: _____ ☐ ***Approval for shipments prior to effective date.***

Name/Date: _____ E-Mail Address: _____

Title: _____ Phone# /Fax# : _____

CUSTOMER COMMENTS: _____

IDT ACKNOWLEDGMENT OF RECEIPT:

RECD. BY: DATE:

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ATTACHMENT - PCN #: L0306-02

PCN Type: Fab Site Change

Data Sheet Change: None

Detail of Change: Transfer existing qualified products to Hillsboro, Oregon Wafer Fab Facility (Fab 4). There is no change in die technology.

The following devices are affected by this change. All packages and speed grades are affected.

Part Number	Old Stepping	New Stepping (Fab 4)
IDTQS32XVH2245	Z	Z4
IDTQS34XVH2245	Z	Z4
IDTQS34XVH245	Z	Z4
IDTQS32X383	Z	Z4
IDTQS32XVH384	Z	Z4
IDTQS3306	Y, QA	Z

Conversion Schedule:

Die Revision	Sample Availability:	Production Shipment:
Z4 Stepping	Available	September 29, 2003
Z Stepping	Available	September 29, 2003

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Qualification Plans: Following reliability tests were performed per process and device families. The qualification results are as follow:

	Required Sample/ # Fails	Process Family Data	Z4 Device Family	Z Device Family
Operating Life Test: Dynamic 1000 hrs @ 125°C or equivalent	116/0	116/0	116/0	116/0
Temperature Cycling 500 Cycles -65°C to +150°C	45/0	45/0	N/A	N/A
Highly Accelerated Stress Test 100 hours	45/0	45/0	N/A	N/A
ESD Human Body Model	3/0	N/A	2500V (3/0)	3500V (3/0)
ESD Charged Device Model	3/0	N/A	1000V (3/0)	1000V (3/0)
Latch up: (Tested to 1.5X Vcc)	10/0	N/A	10/0	10/0

Characterization Data:
Characterization data is available upon request.